

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	75738	(semiconductor chip die dice ic (integrated adj circuit) component electronic) same (electrode pad terminal) same (interconnect interconnection interconnected inteconnecting trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:19
L2	29149	(semiconductor chip die dice ic (integrated adj circuit) component electronic) with (electrode pad terminal) with (interconnect interconnection interconnected inteconnecting trace)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:19
L3	5924	2 with (multi multiple plurality offset tier)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:20
L4	1172	wire same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:30
L5	206	4 and (offset cascade cascading)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:21
L6	0	5 not 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:30
L7	966	4 not 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/28 15:30